

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Attachment materials for electronic assembly –
Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-
fluxed solid solder for electronic soldering applications**

**Matériaux de fixation pour les assemblages électroniques –
Partie 1-3: Exigences relatives aux alliages à braser de catégorie électronique et
brasure solide fluxée et non-fluxée pour les applications de brasage
électronique**



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IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
Fax: +41 22 919 03 00
info@iec.ch
www.iec.ch

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ATTACHMENT MATERIALS FOR ELECTRONIC ASSEMBLY –**Part 1–3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solder for electronic soldering applications**

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International Standard IEC 61190-1-3 has been prepared by IEC technical committee 91: Electronics assembly technology.

This third edition cancels and replaces the second edition, published in 2007 and Amendment 1:2010. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) The maximum impurity level of Pb has been revised and the table of lead free solder alloys includes some additional lead free solder alloys.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1468/FDIS	91/1488/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

A list of all parts in the IEC 61190 series, under the general title *Attachment materials for electronic assembly*, can be found on the IEC website.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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89, Yangdaegiro-gil, Ipjang-myeon, Seobuk-gu, Cheonan-si Chungcheongnam-do 331-822 Korea

KR PAT No.10-0445350
Heesung Material LTD.
820-7, Donghang-ri, Yangseong-Myeon, Anseong-Si, Gyeonggi-Do, 456-931, KOREA

JP PAT No.3152945 , and the foreign patents
Nihon Superior
NS Bldg., 1-16-15 Esaka-Cho, Suita City, Osaka, 564-0063, Japan

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Fuji Electronics
Gate City Ohsaki, East tower 11-2, Osaki 1-Chome, Shinagawa-ku, Tokyo, 141-0032, Japan

JP PAT No. 3736819
Toyota Central R&D Labs., Inc.
41-1, Yokomichi, Nagakute, Aichi 480-1192, Japan
Taiho Kogyo Co., Ltd.
3-65 Midorigaoka Toyota-city, Aichi 471-8502, Japan

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